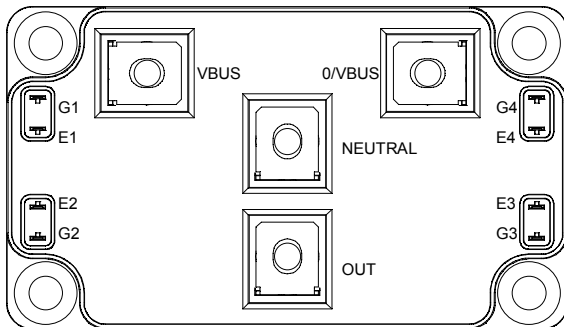
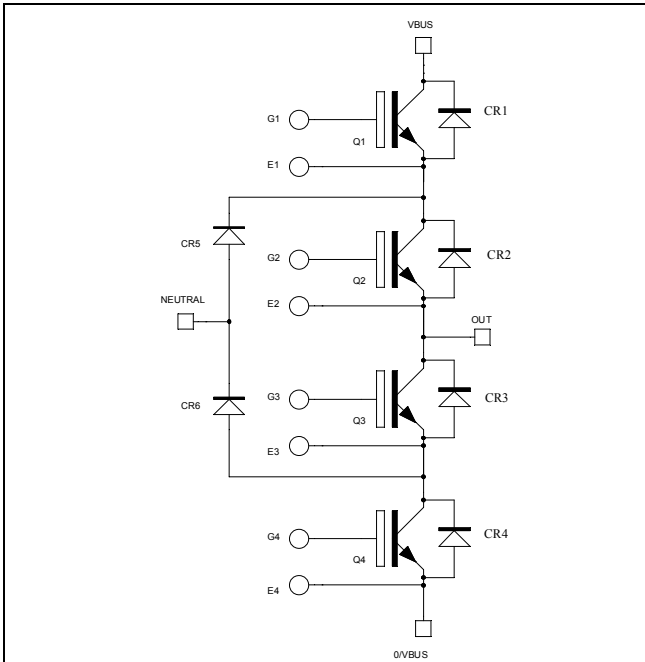


**Three level inverter  
Trench + Field Stop IGBT3  
Power Module**

**$V_{CES} = 600V$   
 $I_C = 300A @ T_c = 80^\circ C$**



**Q1 to Q4 Absolute maximum ratings**

Symbol	Parameter	Max ratings	Unit
$V_{CES}$	Collector - Emitter Breakdown Voltage	600	V
$I_C$	Continuous Collector Current	$T_c = 25^\circ C$	400
		$T_c = 80^\circ C$	300
$I_{CM}$	Pulsed Collector Current	$T_c = 25^\circ C$	600
$V_{GE}$	Gate - Emitter Voltage	$\pm 20$	V
$P_D$	Maximum Power Dissipation	$T_c = 25^\circ C$	935
RBSOA	Reverse Bias Safe Operating Area	$T_j = 150^\circ C$	600A @ 550V

**CAUTION:** These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on [www.microsemi.com](http://www.microsemi.com)

**Application**

- Solar converter
- Uninterruptible Power Supplies

**Features**

- Trench + Field Stop IGBT3 Technology
  - Low voltage drop
  - Low tail current
  - Switching frequency up to 20 kHz
  - Soft recovery parallel diodes
  - Low diode VF
  - Low leakage current
  - RBSOA and SCSOA rated
- Kelvin emitter for easy drive
- Very low stray inductance
  - Symmetrical design
  - M5 power connectors
- High level of integration

**Benefits**

- Stable temperature behavior
- Very rugged
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Easy paralleling due to positive TC of VCEsat
- Low profile
- RoHS Compliant

All ratings @  $T_j = 25^\circ\text{C}$  unless otherwise specified

**Q1 to Q4 Electrical Characteristics**

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
$I_{CES}$	Zero Gate Voltage Collector Current	$V_{GE} = 0\text{V}$ , $V_{CE} = 600\text{V}$			350	$\mu\text{A}$
$V_{CE(sat)}$	Collector Emitter Saturation Voltage	$V_{GE} = 15\text{V}$ $I_C = 300\text{A}$		1.5 1.7	1.9	V
$V_{GE(th)}$	Gate Threshold Voltage	$V_{GE} = V_{CE}$ , $I_C = 5\text{mA}$	5.0	5.8	6.5	V
$I_{GES}$	Gate – Emitter Leakage Current	$V_{GE} = 20\text{V}$ , $V_{CE} = 0\text{V}$			800	nA

**Q1 to Q4 Dynamic Characteristics**

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
$C_{ies}$	Input Capacitance	$V_{GE} = 0\text{V}$		18.4		nF
$C_{oes}$	Output Capacitance	$V_{CE} = 25\text{V}$		1.16		
$C_{res}$	Reverse Transfer Capacitance	$f = 1\text{MHz}$		0.54		
$Q_G$	Gate charge	$V_{GE} = \pm 15\text{V}$ , $I_C = 300\text{A}$ $V_{CE} = 300\text{V}$		3.2		$\mu\text{C}$
$T_{d(on)}$	Turn-on Delay Time	Inductive Switching ( $25^\circ\text{C}$ ) $V_{GE} = \pm 15\text{V}$ $V_{Bus} = 300\text{V}$ $I_C = 300\text{A}$ $R_G = 2.2\Omega$		115		ns
$T_r$	Rise Time			45		
$T_{d(off)}$	Turn-off Delay Time			225		
$T_f$	Fall Time			55		
$T_{d(on)}$	Turn-on Delay Time	Inductive Switching ( $150^\circ\text{C}$ ) $V_{GE} = \pm 15\text{V}$ $V_{Bus} = 300\text{V}$ $I_C = 300\text{A}$ $R_G = 2.2\Omega$		130		ns
$T_r$	Rise Time			50		
$T_{d(off)}$	Turn-off Delay Time			300		
$T_f$	Fall Time			70		
$E_{on}$	Turn on Energy	$V_{GE} = \pm 15\text{V}$ $V_{Bus} = 300\text{V}$		1.7 3		mJ
$E_{off}$	Turn off Energy	$I_C = 300\text{A}$ $R_G = 2.2\Omega$		8.2 10.6		
$I_{sc}$	Short Circuit data	$V_{GE} \leq 15\text{V}$ ; $V_{Bus} = 360\text{V}$ $t_p \leq 6\mu\text{s}$ ; $T_j = 150^\circ\text{C}$		1500		A
$R_{thJC}$	Junction to Case Thermal Resistance				0.16	$^\circ\text{C/W}$

**CR1 to CR4 diode ratings and characteristics**

<i>Symbol</i>	<i>Characteristic</i>	<i>Test Conditions</i>		<i>Min</i>	<i>Typ</i>	<i>Max</i>	<i>Unit</i>
V <sub>RRM</sub>	Maximum Peak Repetitive Reverse Voltage			600			V
I <sub>RM</sub>	Maximum Reverse Leakage Current	V <sub>R</sub> =600V	T <sub>j</sub> = 25°C			150	μA
			T <sub>j</sub> = 150°C			400	
I <sub>F</sub>	DC Forward Current		T <sub>c</sub> = 80°C		200		A
V <sub>F</sub>	Diode Forward Voltage	I <sub>F</sub> = 200A V <sub>GE</sub> = 0V	T <sub>j</sub> = 25°C		1.6	2	V
			T <sub>j</sub> = 150°C		1.5		
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> = 200A V <sub>R</sub> = 300V di/dt = 2800A/μs	T <sub>j</sub> = 25°C		125		ns
			T <sub>j</sub> = 150°C		220		
Q <sub>rr</sub>	Reverse Recovery Charge	I <sub>F</sub> = 200A V <sub>R</sub> = 300V di/dt = 2800A/μs	T <sub>j</sub> = 25°C		9.4		μC
			T <sub>j</sub> = 150°C		19.8		
E <sub>rr</sub>	Reverse Recovery Energy	I <sub>F</sub> = 200A V <sub>R</sub> = 300V di/dt = 2800A/μs	T <sub>j</sub> = 25°C		2.2		mJ
			T <sub>j</sub> = 150°C		4.8		
R <sub>thJC</sub>	Junction to Case Thermal Resistance					0.39	°C/W

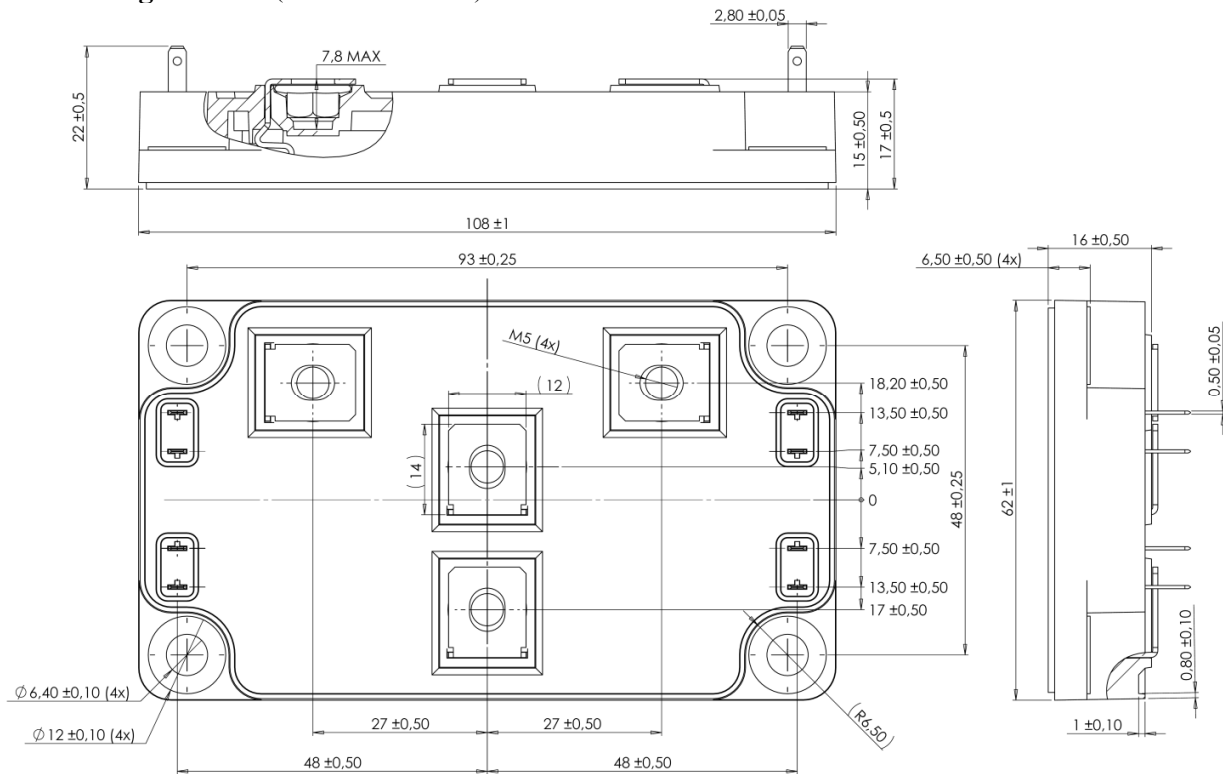
**CR5 & CR6 diode ratings and characteristics**

<i>Symbol</i>	<i>Characteristic</i>	<i>Test Conditions</i>		<i>Min</i>	<i>Typ</i>	<i>Max</i>	<i>Unit</i>
V <sub>RRM</sub>	Maximum Peak Repetitive Reverse Voltage			600			V
I <sub>RM</sub>	Maximum Reverse Leakage Current	V <sub>R</sub> =600V	T <sub>j</sub> = 25°C			150	μA
			T <sub>j</sub> = 150°C			400	
I <sub>F</sub>	DC Forward Current		T <sub>c</sub> = 80°C		300		A
V <sub>F</sub>	Diode Forward Voltage	I <sub>F</sub> = 300A V <sub>GE</sub> = 0V	T <sub>j</sub> = 25°C		1.6	2	V
			T <sub>j</sub> = 150°C		1.5		
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> = 300A V <sub>R</sub> = 300V di/dt = 4000A/μs	T <sub>j</sub> = 25°C		130		ns
			T <sub>j</sub> = 150°C		225		
Q <sub>rr</sub>	Reverse Recovery Charge	I <sub>F</sub> = 300A V <sub>R</sub> = 300V di/dt = 4000A/μs	T <sub>j</sub> = 25°C		13.7		μC
			T <sub>j</sub> = 150°C		29		
E <sub>rr</sub>	Reverse Recovery Energy	I <sub>F</sub> = 300A V <sub>R</sub> = 300V di/dt = 4000A/μs	T <sub>j</sub> = 25°C		3.2		mJ
			T <sub>j</sub> = 150°C		7		
R <sub>thJC</sub>	Junction to Case Thermal Resistance					0.29	°C/W

**Thermal and package characteristics**

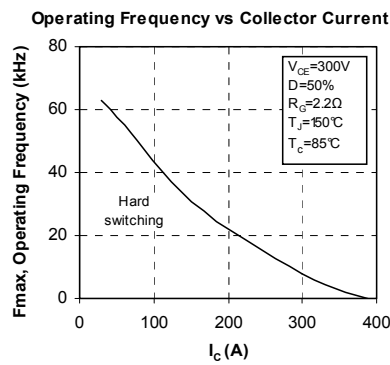
<i>Symbol</i>	<i>Characteristic</i>			<i>Min</i>	<i>Typ</i>	<i>Max</i>	<i>Unit</i>
V <sub>ISOL</sub>	RMS Isolation Voltage, any terminal to case t = 1 min, 50/60Hz			4000			V
T <sub>J</sub>	Operating junction temperature range			-40		175	°C
T <sub>STG</sub>	Storage Temperature Range			-40		125	
T <sub>C</sub>	Operating Case Temperature			-40		100	
Torque	Mounting torque	To heatsink	M6	3		5	N.m
		For terminals	M5	2		3.5	
Wt	Package Weight					300	g

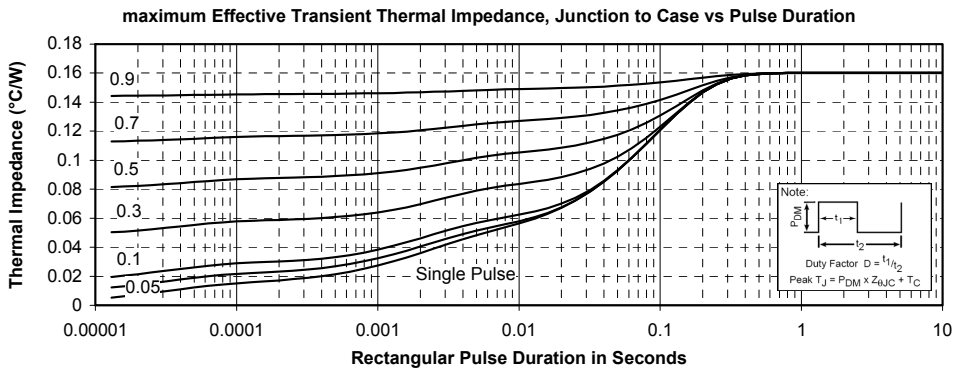
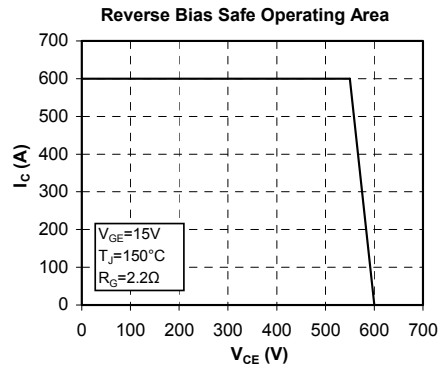
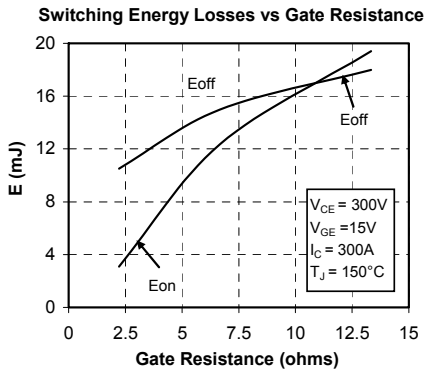
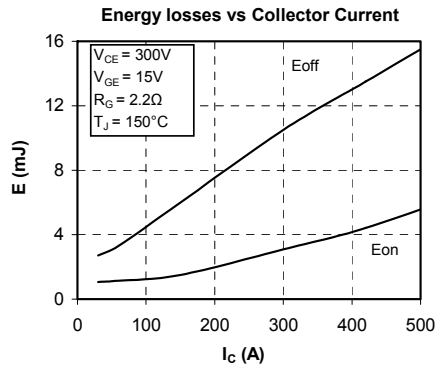
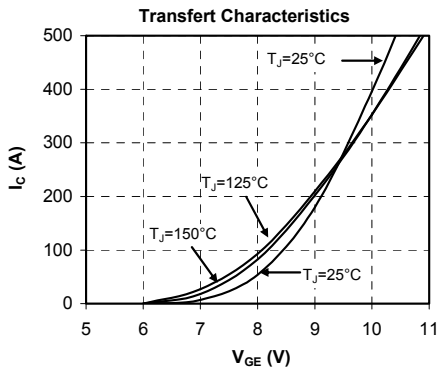
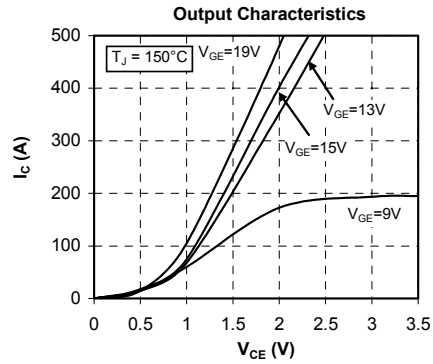
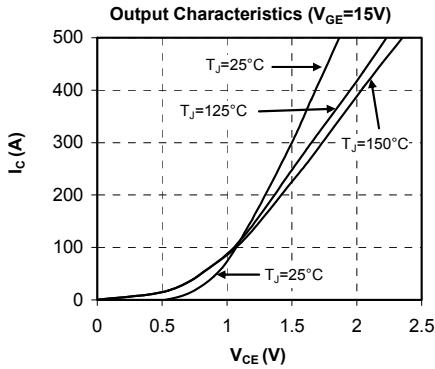
**SP6 Package outline** (dimensions in mm)

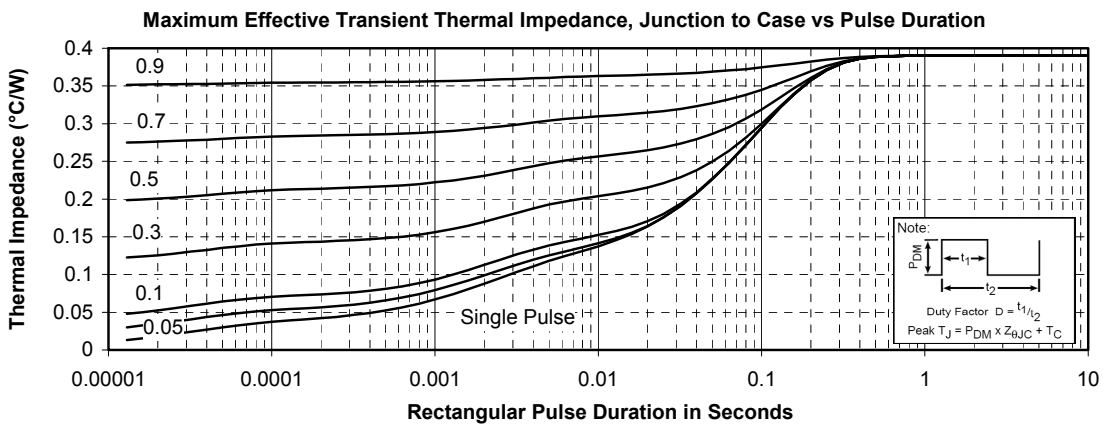
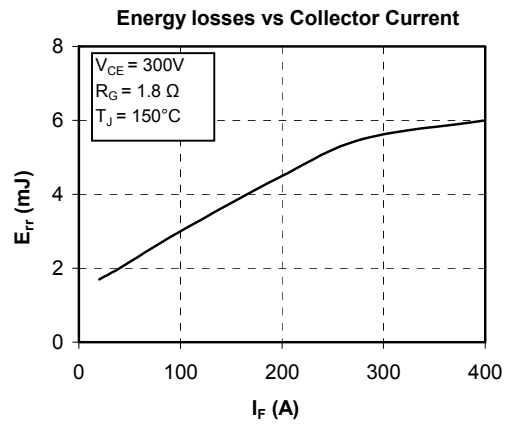
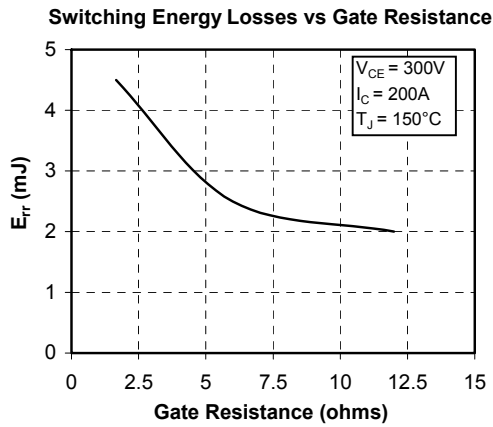
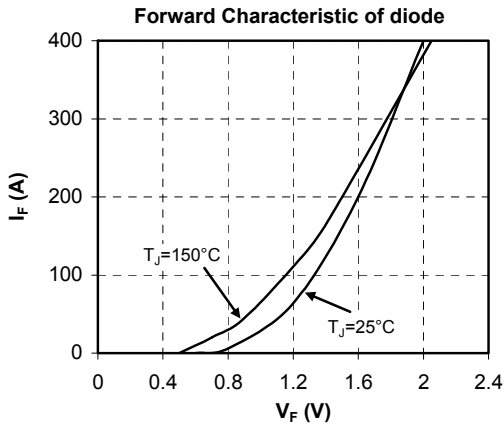


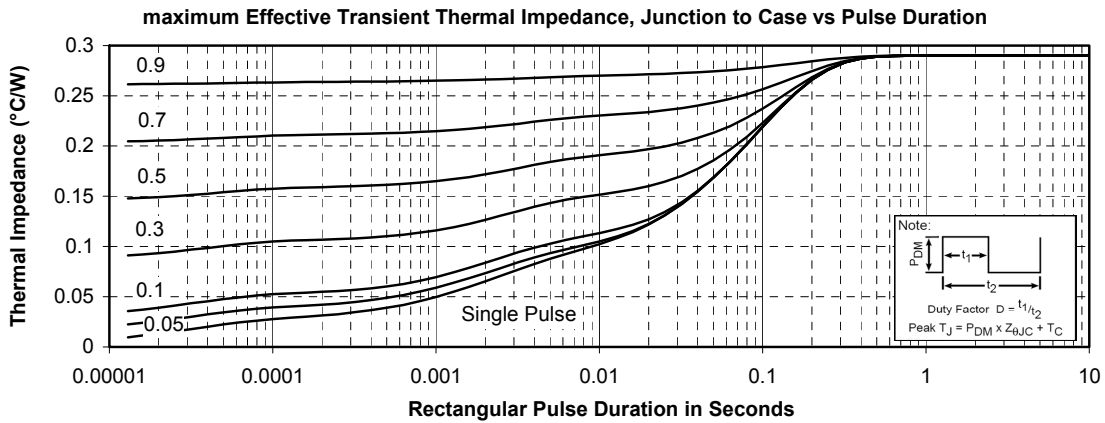
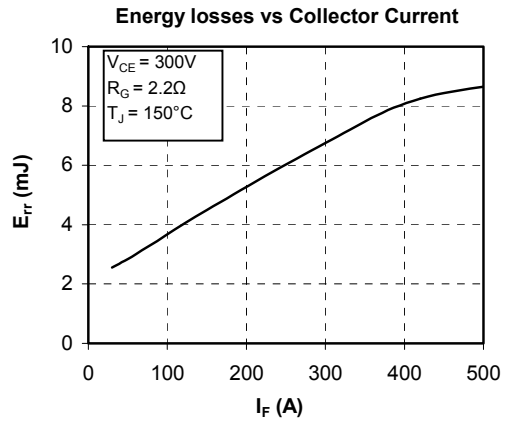
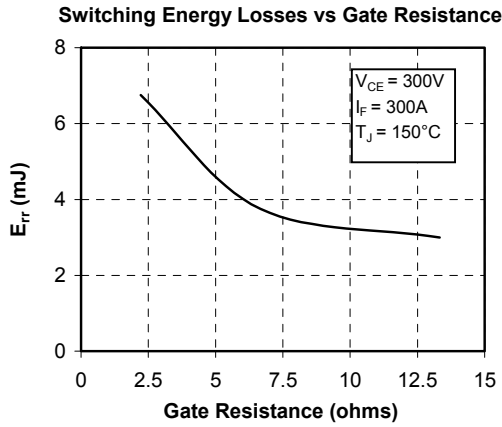
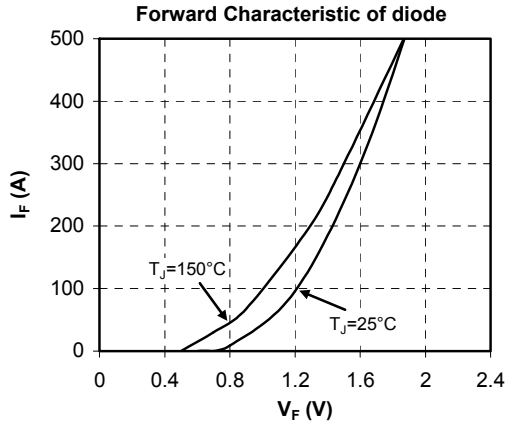
See application note APT0601 - Mounting Instructions for SP6 Power Modules on [www.microsemi.com](http://www.microsemi.com)

**Q1 to Q4 Typical performance curve**





**CR1 to CR4 Typical performance curve**


**CR5 & CR6 Typical performance curve**


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